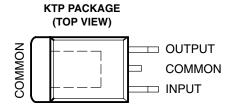
uA78Mxx-Q1 SERIES POSITIVE-VOLTAGE REGULATORS

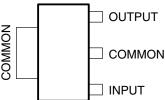
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- **Qualified for Automotive Applications**
- **3-Terminal Regulators**
- **Output Current Up To 500 mA**
- **No External Components**



- **Internal Thermal-Overload Protection**
- **High Power-Dissipation Capability**
- **Internal Short-Circuit Current Limiting**
- **Output Transistor Safe-Area Compensation**

DCY (SOT-223) PACKAGE (TOP VIEW)



description/ordering information

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents and also as the power-pass element in precision regulators.

ORDERING INFORMATION[†]

TJ	V _O (NOM) (V)	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0.0	PowerFLEX™ (KTP)	Reel of 3000	UA78M33QKTPRQ1	78M33CQ
	3.3	SOT-223 (DCY)	Reel of 2500	UA78M33QDCYRQ1	C3Q
	5	PowerFLEX™ (KTP)	Reel of 3000	UA78M05QKTPRQ1	78M05CQ
-40°C to 125°C		SOT-223 (DCY)	Reel of 2500	UA78M05QDCYRQ1	C5Q
	_	PowerFLEX™ (KTP)	Reel of 3000	UA78M08QKTPRQ1	78M08CQ
	8	SOT-223 (DCY)	Reel of 2500	UA78M08QDCYRQ1	C8Q
	10	PowerFLEX™ (KTP)	Reel of 3000	UA78M10QKTPRQ1	78M10CQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.



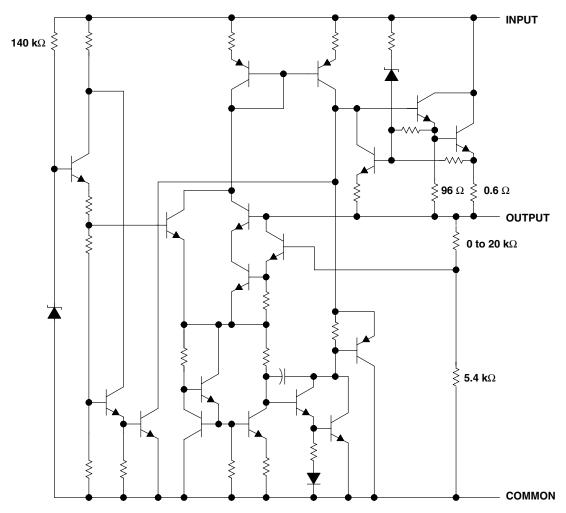
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerFLEX is a trademark of Texas Instruments.



[‡] Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

schematic



Resistor values shown are nominal.



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absolute maximum ratings over virtual junction temperature range (unless otherwise noted)†

Input voltage, V _I	35 V
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq} –65°C to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

package thermal data (see Note 1)

PACKAGE	BOARD	θЈС	θ_{JA}
PowerFLEX (KTP)	High K, JESD 51-5	19°C/W	28°C/W
SOT-223 (DCY)	High K, JESD 51-7	4°C/W	53°C/W

NOTE 1: Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

recommended operating conditions

			MIN	MAX	UNIT
		μ A 78M33	5.3	25	
		μ A 78M05	7	25	
		μΑ78Μ06	8	25	
Vi	i i i i i i i i i i i i i i i i i i i	μ A 78M08	10.5	25	V
		μ A 78M09	11.5	26	
		μΑ78Μ10	12.5	28	
		μ A 78M12	14.5	30	
Io	Output current			500	mA
T_{J}	Operating virtual junction temperature		-40	125	°C

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electrical characteristics at specified virtual junction temperature, V_I = 8 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

DADAMETED		T CONDITIONS!	μ Δ	78M330	ג	LINUT
PARAMETER	TES	ST CONDITIONS†	MIN	TYP	MAX	UNIT
Output with mat	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$		3.2	3.3	3.4	.,
Output voltage [‡]	$V_{I} = 8 \text{ V to } 20 \text{ V}$	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	3.1	3.3	3.5	٧
Land and the manual afficial		V _I = 5.3 V to 25 V		9	100	
Input voltage regulation	I _O = 200 mA	V _I = 8 V to 25 V		3	50	mV
B. 1	$V_1 = 8 \text{ V to } 18 \text{ V},$	$I_{O} = 100 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	62			
Ripple rejection	f = 120 Hz	I _O = 300 mA	62	80		dB
Output voltage regulation	V _I = 8 V,	I _O = 5 mA to 500 mA		20	100	mV
Temperature coefficient of output voltage	$I_O = 5 \text{ mA},$	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV
Dropout voltage				2		V
Bias current				4.5	6	mA
Bias current change	$I_O = 200 \text{ mA},$ $T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	V _I = 8 V to 25 V,			0.8	mA
Ç	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.5	
Short-circuit output current	V _I = 35 V			300		mA
Peak output current			_	700		mA

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

electrical characteristics at specified virtual junction temperature, V_I = 10 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

DADAMETED		T AGUIDITIONS!	μ Δ	78M050	נ	LINIT
PARAMETER	TES	ST CONDITIONS†	MIN	TYP	MAX	UNIT
Output walks as	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$		4.8	5	5.2	V
Output voltage	$V_I = 7 V \text{ to } 20 V$	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	4.75		5.25	V
Input valtage regulation	1 000 mA	V _I = 7 V to 25 V		3	100	mV
Input voltage regulation	I _O = 200 mA	V _I = 8 V to 25 V		1	50	mv
Displa valenties	$V_{i} = 8 V \text{ to } 18 V,$	$I_{O} = 100 \text{ mA}, T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	62			40
Ripple rejection	f = 120 Hz	I _O = 300 mA	62	80		dB
Output with an analytical	$I_O = 5$ mA to 500 mA			20	100	>/
Output voltage regulation	$I_O = 5$ mA to 200 mA			10	50	mV
Temperature coefficient of output voltage	$I_O = 5 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$		-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV
Dropout voltage				2		V
Bias current				4.5	6	mA
Bias current change	$I_O = 200 \text{ mA},$ $T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	V _I = 8 V to 25 V,			0.8	mA
_	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			0.5	
Short-circuit output current	V _I = 35 V			300		mA
Peak output current				0.7		Α

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



[‡] This specification applies only for dc power dissipation permitted by absolute maximum ratings.

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electrical characteristics at specified virtual junction temperature, V_I = 14 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

DADAMETED				μ Δ	78M080	ב	UNIT	
PARAMETER		TEST CONDITIONS†		MIN	TYP	MAX	UNII	
O do do do de la cons	V 40.5.V4-00.V	L 5 A to 050 A		7.7	8	8.3	V	
Output voltage	$V_I = 10.5 \text{ V to } 23 \text{ V},$	$I_O = 5$ mA to 350 mA	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	7.6		8.4	V	
lance de contra de contra de la	L 000 A	V _I = 10.5 V to 25 V			6	100	>/	
Input voltage regulation	I _O = 200 mA	V _I = 11 V to 25 V			2	50	mV	
Discussionalism	$V_I = 11.5 \text{ V to } 21.5 \text{ V},$	I _O = 100 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	56			-ID	
Ripple rejection	f = 120 Hz	$I_O = 300 \text{ mA}$			80		dB	
Output voltage regulation	$I_O = 5 \text{ mA to } 500 \text{ mA}$				25	160		
	I _O = 5 mA to 200 mA				10	80	mV	
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				52		μV	
Dropout voltage					2		V	
Bias current					4.6	6	mA	
Diagram and all and an	V _I = 10.5 V to 25 V,	I _O = 200 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.8		
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$				0.5	mA	
Short-circuit output current	V _I = 35 V				250		mA	
Peak output current					0.7		Α	

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

electrical characteristics at specified virtual junction temperature, V_I = 17 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

24244555				μ Α	78M100	2	
PARAMETER		TEST CONDITIONS†		MIN	TYP	MAX	UNIT
O to to the co	V 40.5 V 4- 05 V			9.6	10	10.4	.,,
Output voltage	$V_I = 12.5 \text{ V to } 25 \text{ V},$	$I_O = 5$ mA to 350 mA	$T_J = -40^{\circ}C$ to $125^{\circ}C$	9.5		10.5	٧
land to alka an an analation	1 000 m A	V _I = 12.5 V to 28 V			7	100	\/
Input voltage regulation	I _O = 200 mA	V _I = 14 V to 28 V			2	50	mV
Ripple rejection	$V_1 = 15 \text{ V to } 25 \text{ V},$	I _O = 100 mA,	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	59			-ID
	f = 120 Hz	I _O = 300 mA		55	80		dB
Output valle are negletter	$I_O = 5 \text{ mA to } 500 \text{ mA}$	I _O = 5 mA to 500 mA			25	200	
Output voltage regulation	$I_O = 5 \text{ mA to } 200 \text{ mA}$				10	100	mV
Temperature coefficient of output voltage	I _O = 5 mA,	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				64		μV
Dropout voltage					2		V
Bias current					4.7	6	mA
5	$V_I = 12.5 \text{ V to } 28 \text{ V},$	I _O = 200 mA,	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.8	
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$					0.5	mA
Short-circuit output current	V _I = 35 V				245		mA
Peak output current					0.7		Α

[†] All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.





24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
UA78M05QDCYRG4Q1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C5Q	Samples
UA78M05QKTPRQ1	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI	-40 to 125		
UA78M33QDCYRG4Q1	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	C3Q	Samples
UA78M33QKTPRQ1	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI	-40 to 125		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF UA78M05-Q1, UA78M33-Q1:

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.





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● Catalog: UA78M05, UA78M33

NOTE: Qualified Version Definitions:

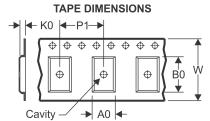
Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA78M05QDCYRG4Q1	SOT-223	DCY	4	2500	330.0	12.4	6.8	7.3	1.88	8.0	12.0	Q3
UA78M33QDCYRG4Q1	SOT-223	DCY	4	2500	330.0	12.4	6.83	7.42	1.88	8.0	12.0	Q3

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA78M05QDCYRG4Q1	SOT-223	DCY	4	2500	358.0	335.0	35.0
UA78M33QDCYRG4Q1	SOT-223	DCY	4	2500	358.0	335.0	35.0

DCY (R-PDSO-G4)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters (inches).

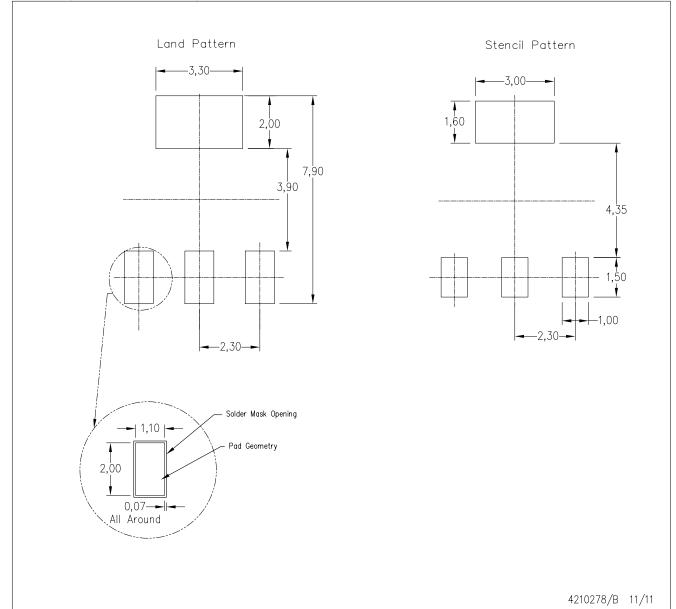
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC TO-261 Variation AA.

DCY (R-PDSO-G4)

PLASTIC SMALL OUTLINE



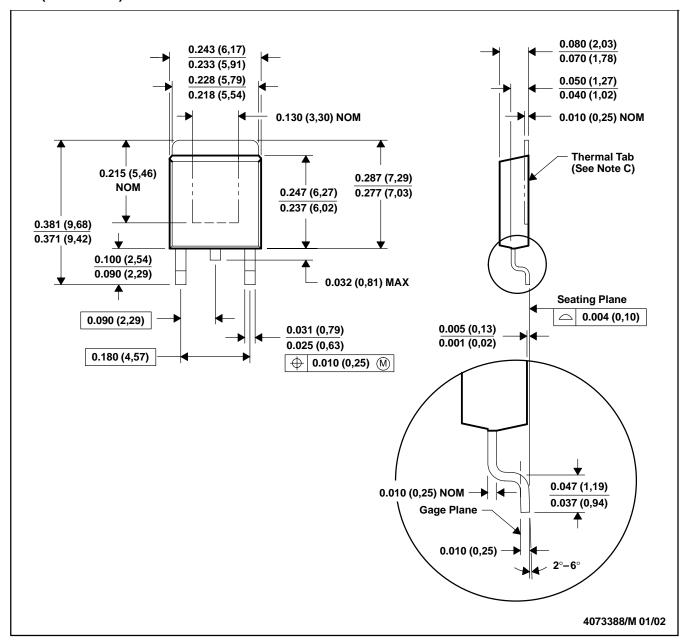
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations.



KTP (R-PSFM-G2)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. The center lead is in electrical contact with the thermal tab.
 - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
 - E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.



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TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

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